

ABSTRACT

In a method of cleaning a surface of a substrate processing chamber component to remove process deposits, the component surface is cooled to a temperature below about -40°C to fracture the process deposits on the surface. The surface can be cooled by immersing the surface in a low temperature fluid, such as liquid nitrogen. In another version, the component surface is heated to fracture and delaminate the deposits, and optionally, subsequently rapidly cooled to form more fractures. The component surface cleaning can also be performed by bead blasting followed by a chemical cleaning step.